2N4403

Preferred Device

General Purpose Transistors

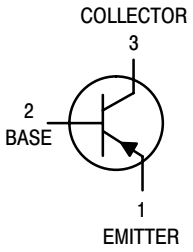
PNP Silicon

ON Semiconductor®

http://onsemi.com

Features

- Pb−Free Packages are Available*



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector − Emitter Voltage	V_{CEO}	40	Vdc
Collector − Base Voltage	V_{CBO}	40	Vdc
Emitter − Base Voltage	V_{EBO}	5.0	Vdc
Collector Current − Continuous	I_C	600	mAdc
Total Device Dissipation @ T_A = 25°C Derate above 25°C	P_D	625 5.0	mW mW/°C
Total Device Dissipation @ T_C = 25°C Derate above 25°C	P_D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150	°C

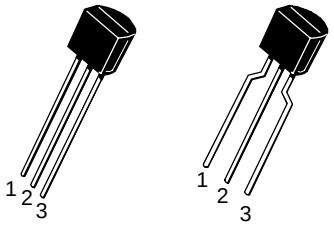
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

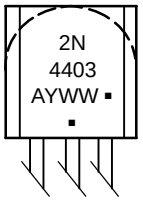
TO−92
CASE 29
STYLE 1



STRAIGHT LEAD
BULK PACK

BENT LEAD
TAPE & REEL
AMMO PACK

MARKING DIAGRAM



2N4403	= Device Code
A	= Assembly Location
Y	= Year
WW	= Work Week
▪	= Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector−Emitter Breakdown Voltage (Note 1)	(I_C = 1.0 mAdc, I_B = 0)	$V_{(BR)CEO}$	40	−	Vdc
Collector−Base Breakdown Voltage	(I_C = 0.1 mAdc, I_E = 0)	$V_{(BR)CBO}$	40	−	Vdc
Emitter−Base Breakdown Voltage	(I_E = 0.1 mAdc, I_C = 0)	$V_{(BR)EBO}$	5.0	−	Vdc
Base Cutoff Current	(V_{CE} = 35 Vdc, V_{EB} = 0.4 Vdc)	I_{BEV}	−	0.1	μAdc
Collector Cutoff Current	(V_{CE} = 35 Vdc, V_{EB} = 0.4 Vdc)	I_{CEX}	−	0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain	(I_C = 0.1 mAdc, V_{CE} = 1.0 Vdc) (I_C = 1.0 mAdc, V_{CE} = 1.0 Vdc) (I_C = 10 mAdc, V_{CE} = 1.0 Vdc) (I_C = 150 mAdc, V_{CE} = 2.0 Vdc) (Note 1) (I_C = 500 mAdc, V_{CE} = 2.0 Vdc) (Note 1)	h_{FE}	30 60 100 100 20	− − − 300 −	−
Collector−Emitter Saturation Voltage (Note 1)	(I_C = 150 mAdc, I_B = 15 mAdc) (I_C = 500 mAdc, I_B = 50 mAdc)	$V_{CE(sat)}$	− −	0.4 0.75	Vdc
Base−Emitter Saturation Voltage (Note 1)	(I_C = 150 mAdc, I_B = 15 mAdc) (I_C = 500 mAdc, I_B = 50 mAdc)	$V_{BE(sat)}$	0.75 −	0.95 1.3	Vdc
SMALL−SIGNAL CHARACTERISTICS					
Current−Gain − Bandwidth Product	(I_C = 20 mAdc, V_{CE} = 10 Vdc, f = 100 MHz)	f_T	200	−	MHz
Collector−Base Capacitance	(V_{CB} = 10 Vdc, I_E = 0, f = 1.0 MHz)	C_{cb}	−	8.5	pF
Emitter−Base Capacitance	(V_{EB} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)	C_{eb}	−	30	pF
Input Impedance	(I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{ie}	1.5 k	15 k	Ω
Voltage Feedback Ratio	(I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{re}	0.1	8.0	X 10^{-4}
Small−Signal Current Gain	(I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{fe}	60	500	−
Output Admittance	(I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)	h_{oe}	1.0	100	μmhos
SWITCHING CHARACTERISTICS					
Delay Time	(V_{CC} = 30 Vdc, V_{BE} = +2.0 Vdc, I_C = 150 mAdc, I_{B1} = 15 mAdc)	t_d	−	15	ns
Rise Time		t_r	−	20	ns
Storage Time	(V_{CC} = 30 Vdc, I_C = 150 mAdc, I_{B1} = 15 mA, I_{B2} = 15 mA)	t_s	−	225	ns
Fall Time		t_f	−	30	ns

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device	Package	Shipping†
2N4403	TO−92	5000 Units / Bulk
2N4403G	TO−92 (Pb−Free)	5000 Units / Bulk
2N4403RLRA	TO−92	2000 / Tape & Reel
2N4403RLRAG	TO−92 (Pb−Free)	2000 / Tape & Reel
2N4403RLRM	TO−92	2000 / Ammo Pack
2N4403RLRMG	TO−92 (Pb−Free)	2000 / Ammo Pack
2N4403RLRPG	TO−92 (Pb−Free)	2000 / Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SWITCHING TIME EQUIVALENT TEST CIRCUIT

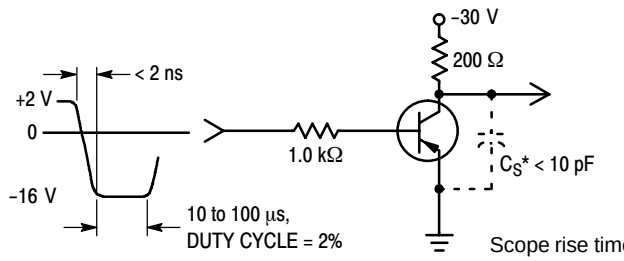


Figure 1. Turn−On Time

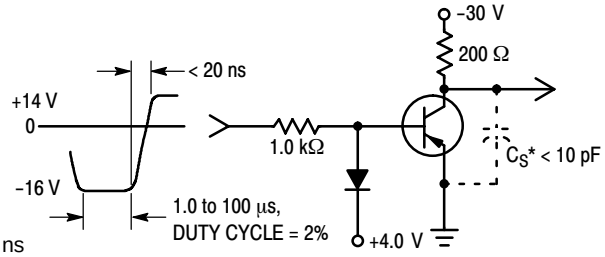


Figure 2. Turn−Off Time

Scope rise time < 4.0 ns
*Total shunt capacitance of test jig connectors, and oscilloscope

TRANSIENT CHARACTERISTICS

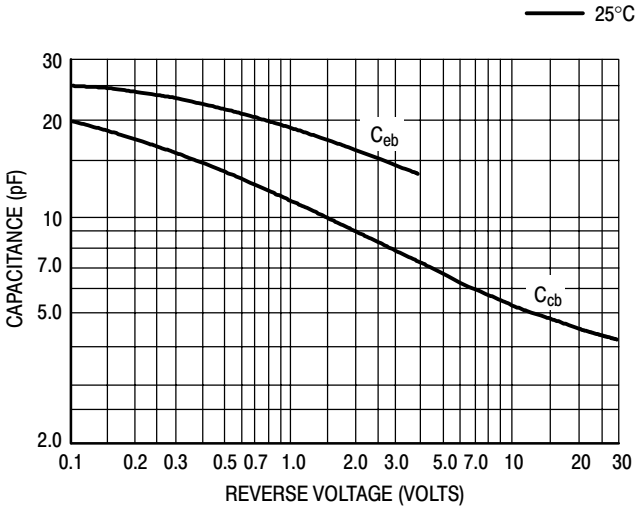


Figure 3. Capacitances

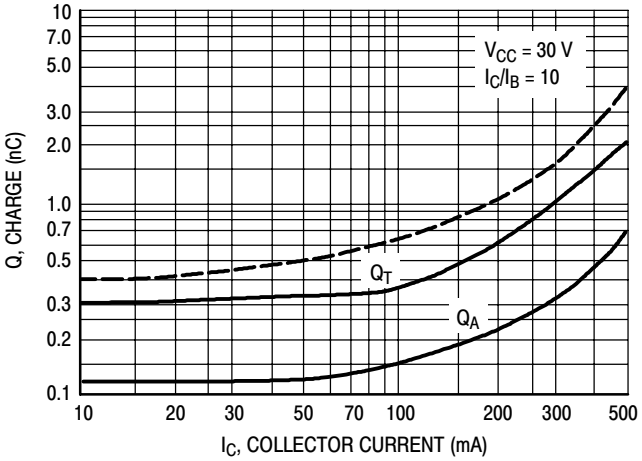


Figure 4. Charge Data

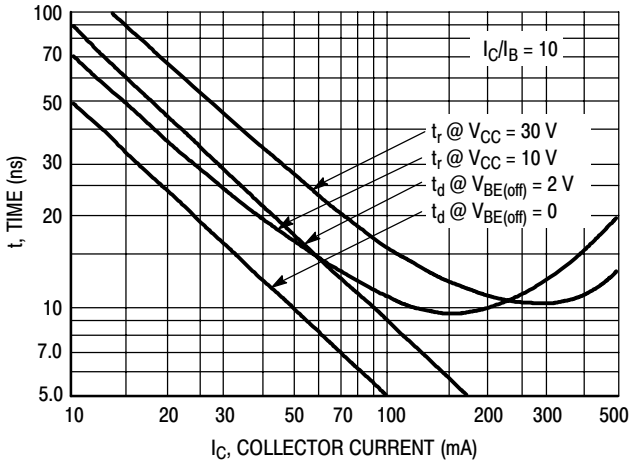


Figure 5. Turn−On Time

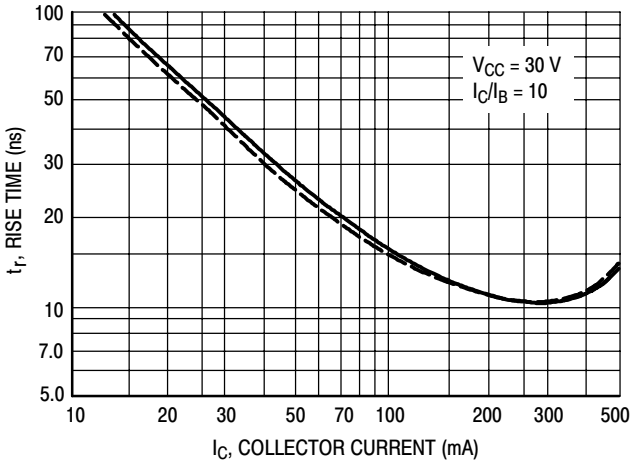


Figure 6. Rise Time

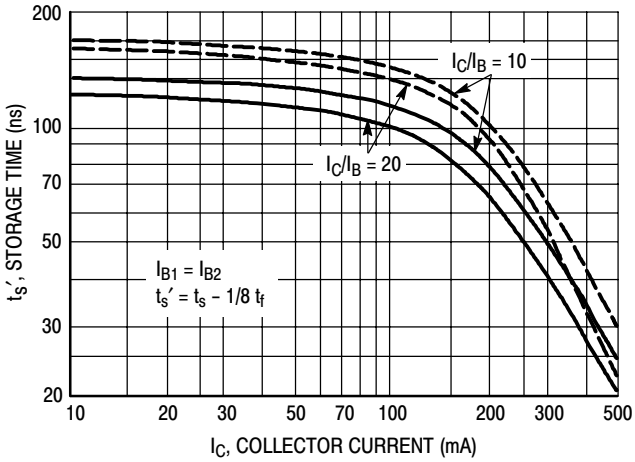


Figure 7. Storage Time

SMALL−SIGNAL CHARACTERISTICS

NOISE FIGURE

V_{CE} = −10 Vdc, T_A = 25°C; Bandwidth = 1.0 Hz

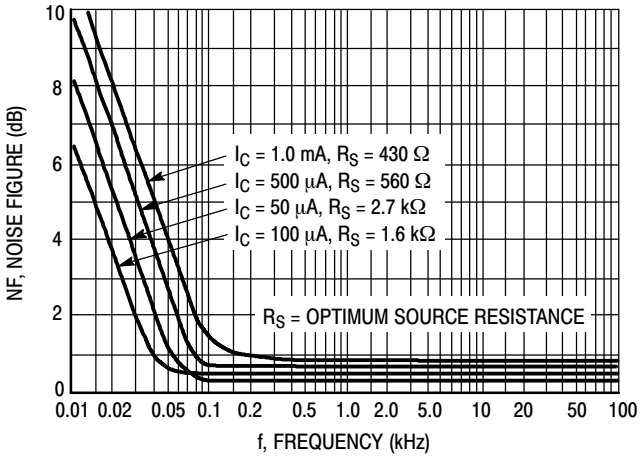


Figure 8. Frequency Effects

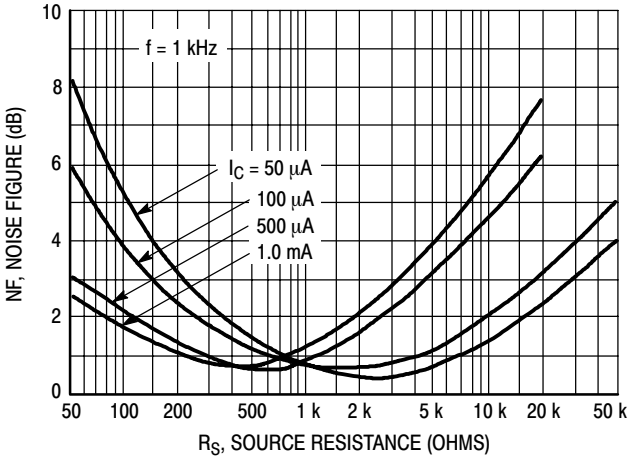


Figure 9. Source Resistance Effects

h PARAMETERS

V_{CE} = −10 Vdc, f = 1.0 kHz, T_A = 25°C

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high−gain and a low−gain unit were selected from the 2N4403 lines, and the same units were used to develop the correspondingly−numbered curves on each graph.

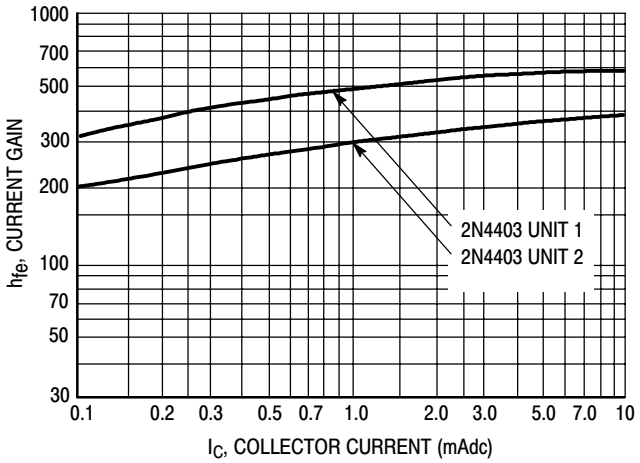


Figure 10. Current Gain

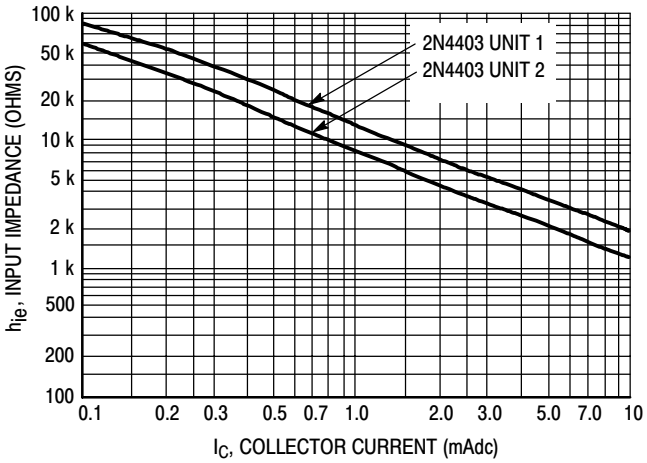


Figure 11. Input Impedance

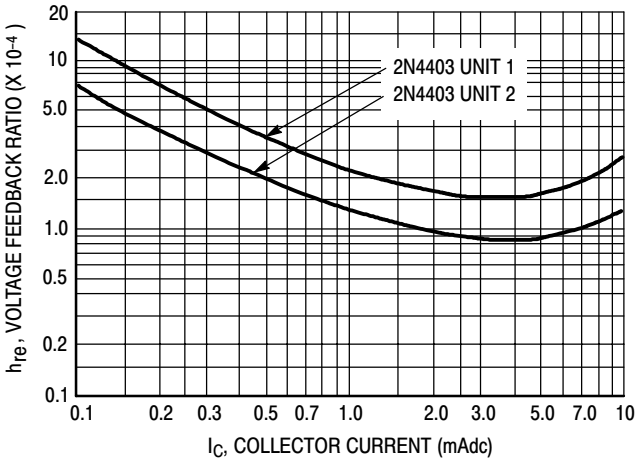


Figure 12. Voltage Feedback Ratio

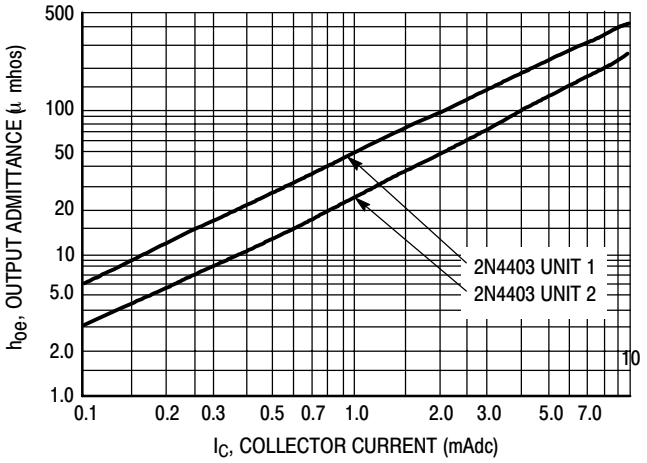


Figure 13. Output Admittance

STATIC CHARACTERISTICS

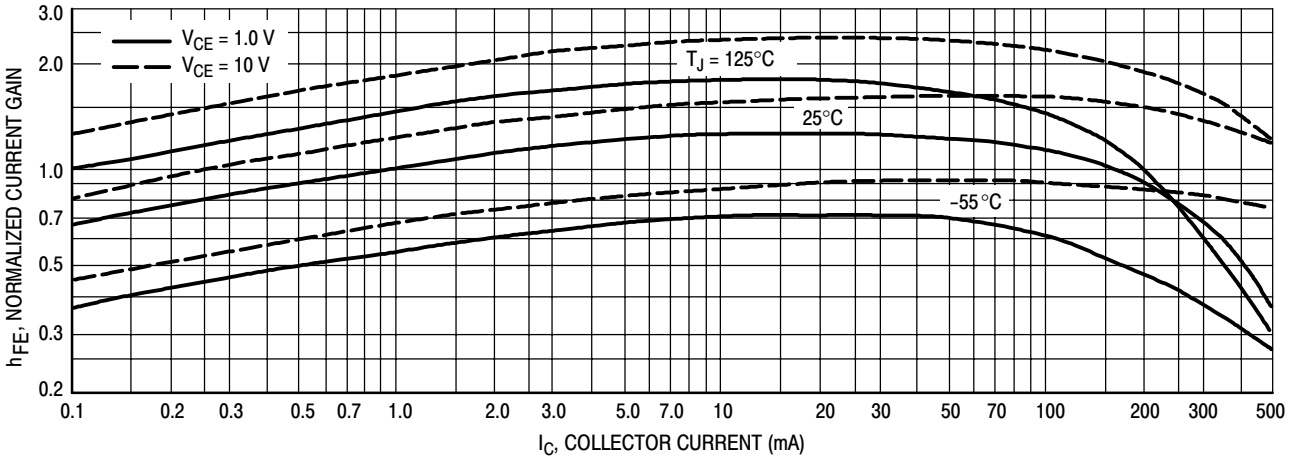


Figure 14. DC Current Gain

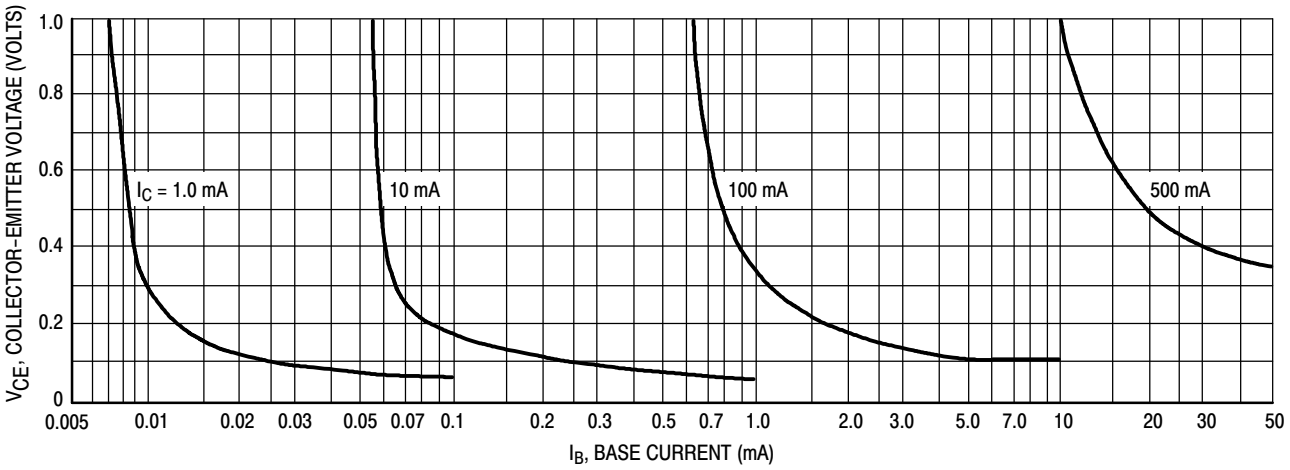


Figure 15. Collector Saturation Region

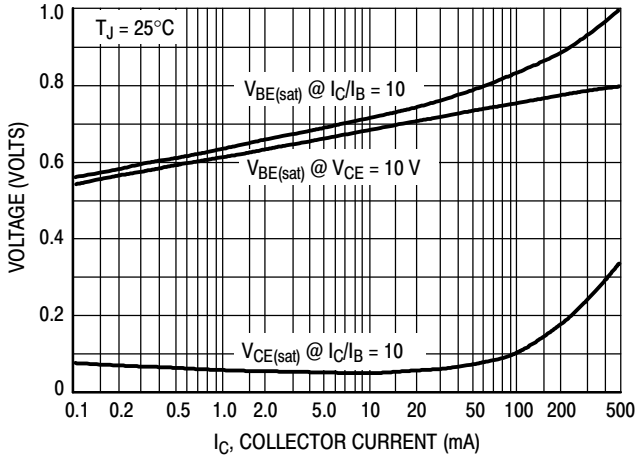


Figure 16. “On” Voltages

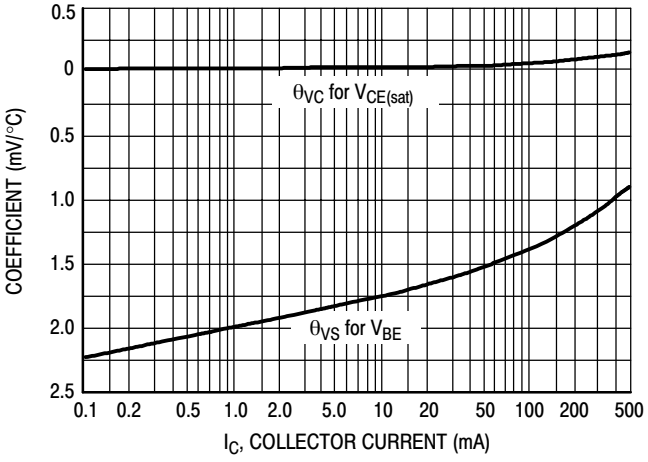
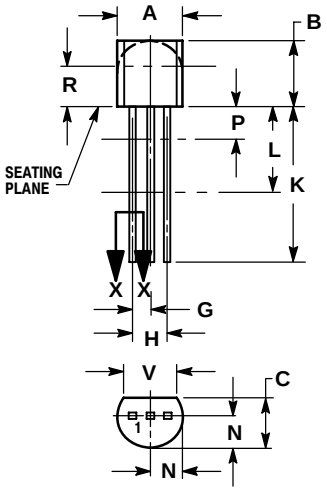


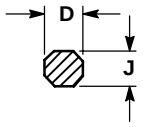
Figure 17. Temperature Coefficients

PACKAGE DIMENSIONS

TO−92 (TO−226)
CASE 29−11
ISSUE AM



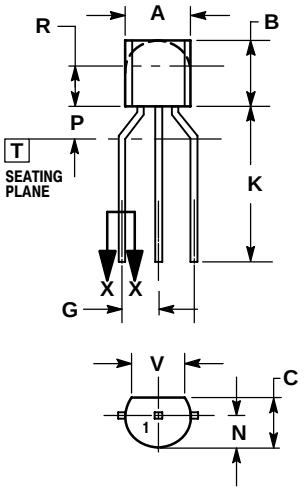
STRAIGHT LEAD
BULK PACK



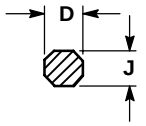
SECTION X−X

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X−X

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS	
DIM	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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2N4403/D